

LINEAR TECHNOLOGY MATERIALS DECLARATION

(Engineering Calculation)

DFN 4mm X 3mm Exp. Pad

LTC2636CDE-LM18#PBF

(printed on: 2014-01-19 23:45:49)

TOTAL MASS (g): 0.03175

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001752	1000000	55181.5		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013133	975000	413640.78125		
		Iron (Fe)	7439-89-6	0.000223	24000	10173.3007812		
		Phosphorus (P)	7723-14-0	0.000004	300	125.985108457		
		Zinc (Zn)	7440-66-6	0.000009	700	281.46661377		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.013469</b>	<b>1000000</b>	<b>424223.53125</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000626	1000000	19709.2925781		
		<b>External Plating Total:</b>				<b>0.000626</b>	<b>1000000</b>	<b>19709.2925781</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000002	1000000	9511.87988281		
		<b>Internal Plating Total:</b>				<b>0.000002</b>	<b>1000000</b>	<b>9511.87988281</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000836	750000	26330.9003906		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000279	250000	8787.46484375		
		<b>Die Attach Total:</b>				<b>0.001115</b>	<b>1000000</b>	<b>35116.3622812</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.001876	130000	59087.0429688
Bromine (Br)	40093-93-8			0.000000	0	0		
Silica (SiO2)	60676-86-0			0.012410	860000	390868.96875		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000000	0	0		
Carbon Black (C)	1333-86-4			0.000144	10000	4555.46582031		
<b>Encapsulation Total:</b>						<b>0.014430</b>	<b>1000000</b>	<b>45491.5</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000056	1000000	1763.7923584		

TOTAL MASS (g): 0.031750